What is claimed is:

1. A soldering method comprising the steps of:

bonding a first electronic component having electrodes plated with a material containing lead to one surface of an interconnect substrate through solder containing no lead;

flow-soldering to bond a second electronic component to the other surface of the interconnect substrate; and

heating a joint section between the first electronic component and the interconnect substrate at the same time as or after the step of flow-soldering to melt the joint section.

2. The soldering method as defined in claim 1,

wherein the step of heating the joint section is performed at the same time as the step of flow soldering.

3. The soldering method as defined in claim 1,

wherein the step of heating the joint section is performed after the step of flow soldering.

4. The soldering method as defined in claim 1,

wherein the step of heating the joint section is performed both at the same time as and after the step of flow soldering.

5. The soldering method as defined in claim 1,

wherein the step of heating the joint section is performed by at least one of radiant heat and a hot blast.

6. The soldering method as defined in claim 1,

wherein the first electronic component is bonded to one surface of the interconnect substrate by reflow soldering.

7. The soldering method as defined in claim 1,

wherein the first electronic component is bonded to one surface of the interconnect substrate by hand soldering.

8. The soldering method as defined in claim 1, further comprising:

a step of preheating the joint section before the step of flow soldering.

9. The soldering method as defined in claim 1,

wherein the solder containing no lead is formed of at least one material selected from a group consisting of tin, silver, copper, zinc, and bismuth.

10. The soldering method as defined in claim 1,

wherein at least the step of heating the joint section is performed in a chamber.

11. A method of fabricating an electronic circuit module,

wherein the first and second electronic components are mounted on the interconnect substrate by the soldering method as defined in claim 1.

12. A soldering device comprising:

a flow soldering section, when a first electronic component having electrodes plated with a material containing lead is bonded to one surface of an interconnect substrate through solder containing no lead, bonds a second electronic component to the other surface of the interconnect substrate,

wherein the flow soldering section includes a heater disposed on the side of a surface of the interconnect substrate to which the first electronic component is bonded, to melt a joint section between the first electronic component and the interconnect substrate.

13. The soldering device as defined in claim 12,

wherein the flow soldering section has a solder supplying section disposed on the side of the other surface of the interconnect substrate; and

wherein the heater is disposed above the solder supplying section.

14. The soldering device as defined in claim 12,

wherein the flow soldering section has a solder supplying section disposed on the side of the other surface of the interconnect substrate; and

wherein the heater is disposed downstream from the solder supplying section in a direction in which the interconnect substrate is transferred.

15. The soldering device as defined in claim 12,

wherein the flow soldering section has a solder supplying section disposed on the side of the other surface of the interconnect substrate; and

wherein the heater is disposed above the solder supplying section or downstream from the solder supplying section in a direction in which the interconnect substrate is transferred.

16. The soldering device as defined in claim 12, comprising a plurality of the heaters,

wherein the flow soldering section has a solder supplying section disposed on the side of the other surface of the interconnect substrate;

wherein part of the heaters is disposed above the solder supplying section; and

wherein another part of the heaters is disposed downstream from the solder supplying section in a direction in which the interconnect substrate is transferred.

17. The soldering device as defined in claim 12, comprising:

a plurality of the heaters, wherein at least one of the heaters is a far infrared heater.

18. The soldering device as defined in claim 12, further comprising a fan.

19. The soldering device as defined in claim 12, further comprising:

a reflow soldering section for bonding the first electronic component to one surface of the interconnect substrate.

20. The soldering device as defined in claim 12, further comprising:

a second heater for preheating the joint section before flow soldering.

21. The soldering device as defined in claim 12, further comprising:

a chamber in which at least the flow soldering section is disposed.

22. A device of fabricating an electronic circuit module comprising the soldering device as defined in claim 12,

wherein the first and second electronic components are mounted on the interconnect substrate.